© Copyri	ial Composition ight 2005. IPC, Banno onal and Pan-America	ockburn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	vithin the manufactu level materials for v	rer listed i which the n	tem. Note:	if the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	als and Mfg Information				
Supplier Information														
Company name* Con			Company unique ID			Unique ID Authority				Respons	Response Date*			
onsemi										2023-06	2023-06-08			
Contact Name Title - Co			e - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards Prod			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - H			itle - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com				
Requester Item Num			Number Mfr Item Name			Effective Date	Version	Version Manufacturing Site			Weight*	UOM	Unit Type	
	FDM	DMF5826DC Smart Power S		Stage Module		2023-06-08		PI	PBB		85.215	mg	Each	
<b>Manufacturing Proccess</b>	Information													
Terminal Plating / Gr	Terminal Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Pea		Temperature Number of Reflow Cycles						
Matte Tin (Sn) - annealed CU		CU Alloy	1			260	260 C		30 seco		seconds 3			
omments														
vel 1 - maximum time at peak	<u>k temperature during</u>	g soldering is 10-3	0 seconds											
or more information regardin	ng material composit	ion please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip (Heat sink)	26.983	mg	Supplier	Zinc (Zn)	7440-66-6		0.035	mg
			Supplier	Iron (Fe)	7439-89-6		0.648	mg
			Supplier	Copper (Cu)	7440-50-8		26.3	mg
Die	1.31	mg	Supplier	Silicon (Si)	7440-21-3		1.31	mg
Die Attach Solder	3.524	mg	Supplier	Silver (Ag)	7440-22-4		0.0881	mg
			А	Lead (Pb)	7439-92-1	7a	3.2597	mg
			Supplier	Tin (Sn)	7440-31-5		0.1762	mg
Lead Frame	27.291	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
			Supplier	Zinc (Zn)	7440-66-6		0.036	mg
			Supplier	Iron (Fe)	7439-89-6		0.655	mg
			Supplier	Copper (Cu)	7440-50-8		26.3	mg
Mold Compound-Black	23.412	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		2.11	mg
			Supplier	Carbon Black (C)	1333-86-4		0.234	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.6	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.468	mg
Plating	1.73	mg	Supplier	Tin (Sn)	7440-31-5		1.73	mg
Wire Bond - Au	0.088	mg	Supplier	Gold (Au)	7440-57-5		0.088	mg
Wire Bond - Cu	0.877	mg	Supplier	Palladium (Pd)	7440-05-3		0.0175	mg
			Supplier	Copper (Cu)	7440-50-8		0.8595	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).